

/ Descriptions

SOD-323
Schottky Diode in a SOD-323 Plastic Package.

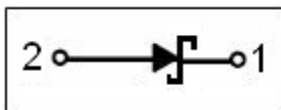
/ Features

Schottky diodes. HF Product.

/ Applications

Small signal diode.

/ Equivalent Circuit



/ Pinning



PIN1:Cathode PIN2:Anode

/ h_{FE} Classifications & Marking

Marking	H86
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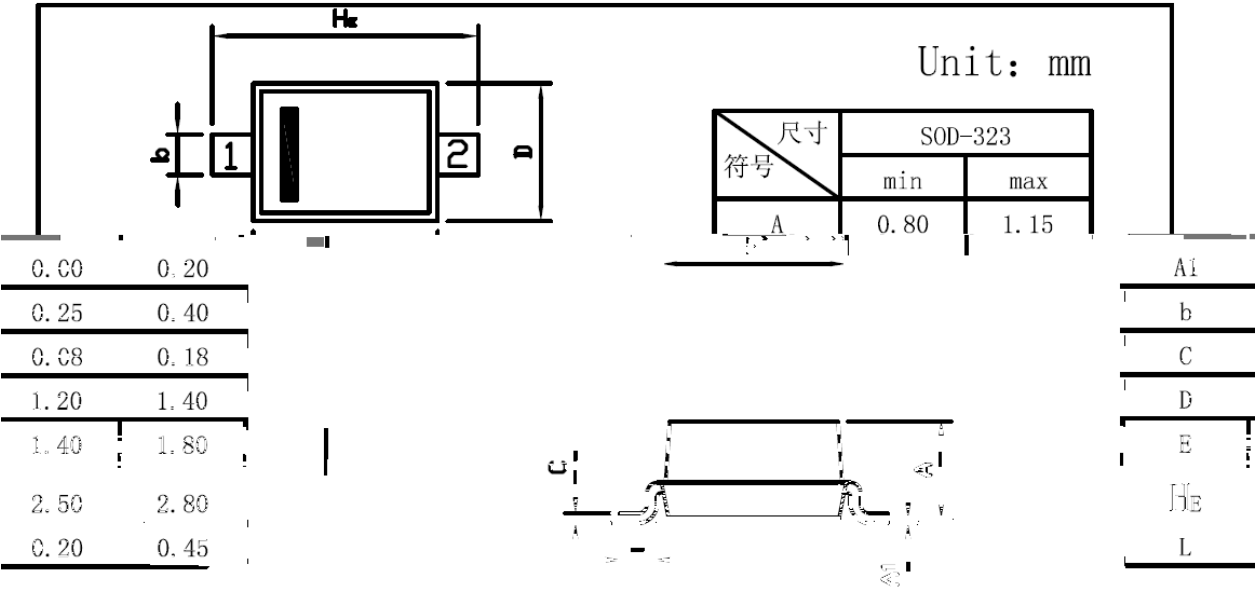
/ Absolute Maximum Ratings(Ta=25)

Parameter	Symbol	Rating	Unit
Repetitive peak reverse voltage	V_{RRM}	30	V
Continuous forward current	I_F	200	mA
Surge non repetitive forward current	I_{FSM}	600	mA
Power Dissipation	P_D	250	mW
Typical Thermal Resistance Junction to Ambient	$R_{\theta JA}$	430	/W
Junction Temperature Range	T_J	150	
Storage Temperature Range	T_{stg}	-55 150	

/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Rating		Unit
			MIN	MAX	
Reverse Voltage	V_R	$I_R=10\mu A$	30		V
Peak Forward voltage	V_F	$I_F=0.1mA$		240	mV
		$I_F=1.0mA$		320	mV
		$I_F=10mA$		400	mV
		$I_F=30mA$		500	mV
		$I_F=100mA$		0.8	V
Instantaneous Reverse Current	I_R	$V_R=25V$		2.0	μA
Total capacitance	C_T	$V_R=1.0V$ $f=1.0MHz$		10	pF
Reverse recovery time	t_{rr}	$I_{RR}=1.0mA$ $R_L=100\Omega$ $I_F=10mA$		5.0	ns

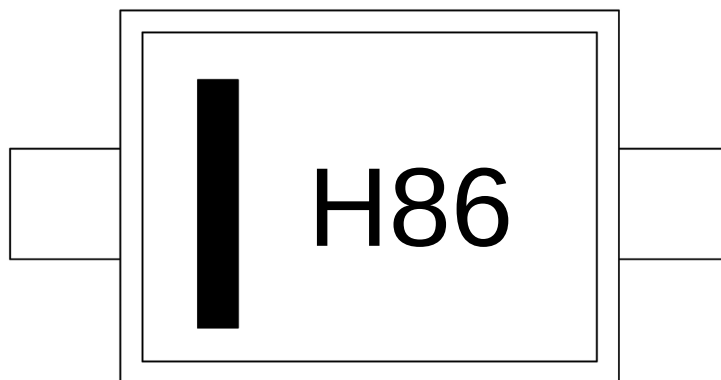
/ Package Dimensions



PIN 1CA 1 2AN 2

SOD-323

/ Marking Instructions



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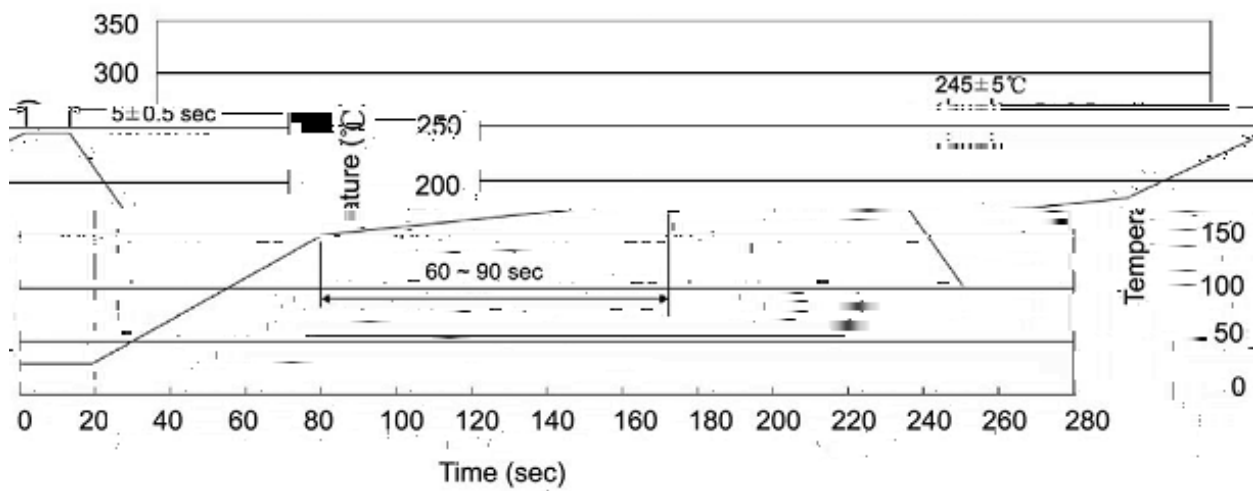
86

Note:

H: Company Code.

86: Product Type.

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- 1

150 180

60 90sec;

1.Preheating: 150 180 , Time:60~90sec.
- 2

245±5

5±0.5sec;

2.Peak Temp.:245±5 , Duration:5±0.5sec.
- 3

2 10 /sec.

3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOD-323	3,000	10	30,000	6	180,000	7 ×8	180×120×180	390×385×205

/ Notices